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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HAMASAKI, et al.

Atty. Dkt.: 01-615

Serial No.: 10/814,180

Art Unit: 2825

Filed: April 1, 2004

Examiner: MALSAWMA

Title: METHOD OF RESIN-SEALING A
SEMICONDUCTOR DEVICE, AND
FORMING DIE FOR RESIN SEALING
THE SEMICONDUCTOR DEVICE

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Window, Mail Stop Amendment
Randolph Building
401 Dulany St.
Alexandria, VA 22314

Date: 25 February 2005

AMENDMENT UNDER 37 CFR 1.111

Sir:

In response to the office action mailed 19 November 2004, please amend the application
as follows:

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of
this paper.

Remarks begin on page 5 of this paper.